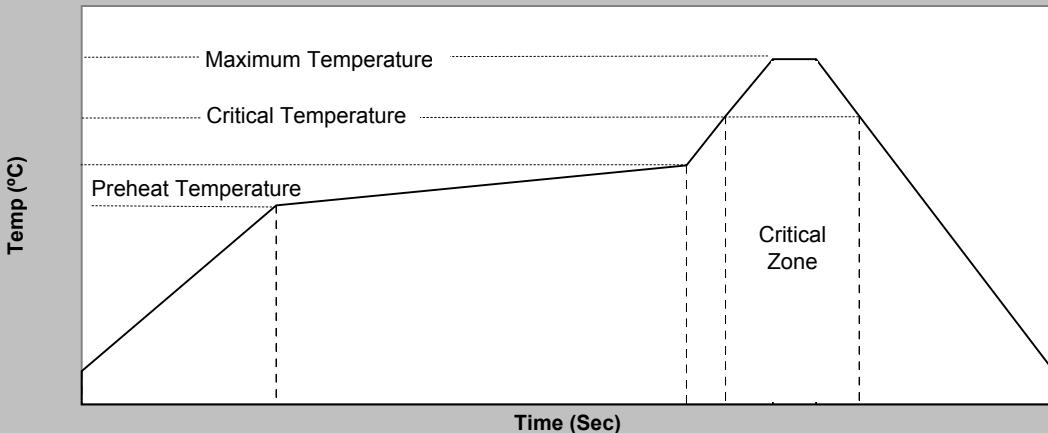


Reflow Profile



Temperature and time recommendations

Tin-Nickel Plating using Pb free solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Tin-Nickel Plating using Pb solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 245°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Gold Plating using Pb free solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Gold Plating using Pb solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 235°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Tin Plating using Pb free solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Silver Plating using Pb free solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Tin Plating using Pb solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 235°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Silver Plating using Pb solder

Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 235°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Disclaimer

Keystone Electronics Corp. does not assume any liability arising out of the use or application of the information given. Every effort is made to ensure that technical specifications are accurate. However technical specifications included herein should be used for reference only. Many factors such as circuit board thickness, size, semiconductor packages and reflow equipment are some factors that affect the total profile time.

Keystone Electronics reserve the right to make changes to the products without notice to improve reliability, design or function.